

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau



10/534330

(43) International Publication Date
21 May 2004 (21.05.2004)

PCT

(10) International Publication Number
WO 2004/042818 A1

(51) International Patent Classification⁷: H01L 23/485 (81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(21) International Application Number: PCT/IB2003/004877

(22) International Filing Date: 31 October 2003 (31.10.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 02102552.3 8 November 2002 (08.11.2002) EP

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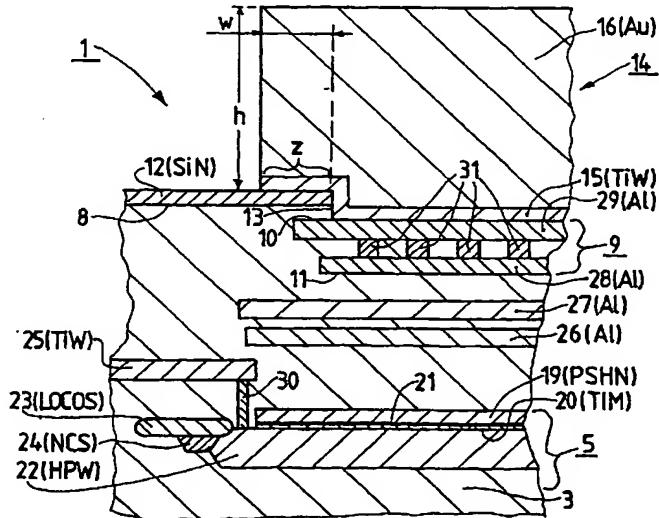
(84) Designated States (regional): ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: INTEGRATED CIRCUIT WITH AT LEAST ONE BUMP



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(57) Abstract: In an integrated circuit (1) having a substrate (3) and having a signal-processing circuit (4) which is produced at a surface (8) of the substrate (3), there is provided on the substrate surface (8) a protective layer (12) that has at least one aperture (13) through which a second contact pad (14) is electrically and mechanically connected to a first contact pad (9), wherein the second contact pad (14) is of a height of at least 15 μm and projects laterally beyond the aperture (13) on all sides and is seated on the protective layer (12) by an overlap zone (z) that is closed on itself like a ring, wherein the overlap zone (z) has a constant width of overlap (w) of between 2 μm and 15 μm, and wherein at least one element of the signal-processing circuit (4), and preferably only one capacitor (5) of the signal-processing circuit (4), is provided opposite the first contact pad (9).